

## MOS FIELD EFFECT TRANSISTOR

3SK222

# RF AMPLIFIER FOR FM TUNER AND VHF TV TUNER N-CHANNEL SI DUAL GATE MOS FIELD-EFFECT TRANSISTOR 4 PINS MINI MOLD

#### **FEATURES**

• The Characteristic of Cross-Modulation is good. CM = 92 dB $\mu$  TYP. @ f = 200 MHz, GR = -30 dB

• Low Noise Figure: NF1 = 1.2 dB TYP. (f = 200 MHz)

NF2 = 1.0 dB TYP. (f = 55 MHz)

• High Power Gain: GPS = 23 dB TYP. (f = 200 MHz)

Enhancement Type.

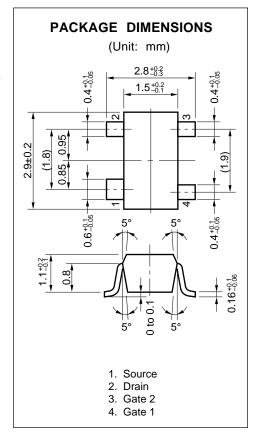
• Suitable for use as RF amplifier in FM tuner and VHF TV tuner.

Automatically Mounting: Embossed Type Taping

Small Package: 4 Pins Mini Mold

#### ABSOLUTE MAXIMUM RATINGS (TA = 25 $^{\circ}$ C)

Drain to Source Voltage	VDSX	18	V
Gate1 to Source Voltage	V <sub>G1</sub> s	±8 (±10)*1	V
Gate2 to Source Voltage	V <sub>G2</sub> S	±8 (±10)*1	V
Gate1 to Drain Voltage	$V_{G1D}$	18	V
Gate2 to Drain Voltage	$V_{G2D}$	18	V
Drain Current	ΙD	25	mΑ
<b>Total Power Dissipation</b>	Po	200	mW
Channel Temperature	Tch	125	°C
Storage Temperature	Tstg	-55 to +125	°C
*1 R <sub>L</sub> $\geq$ 10 k $\Omega$			



#### **PRECAUTION**

Avoid high static voltages or electric fields so that this device would not suffer from any damage due to those voltage or fields.



## ELECTRICAL CHARACTERISTICS (Ta = 25 $^{\circ}$ C)

CHARACTERISTIC	SYMBOL	MIN.	TYP.	MAX.	UNIT	TEST CONDITIONS
Drain to Source Breakdown Voltage	BV <sub>DSX</sub>	18			V	$V_{G1S} = V_{G2S} = -2 \text{ V, ID} = 10 \ \mu\text{A}$
Drain Current	IDSX	0.01		8.0	mA	V <sub>DS</sub> = 6 V, V <sub>G2S</sub> = 3 V, V <sub>G1S</sub> = 0.75 V
Gate1 to Source Cutoff Voltage	V <sub>G1S(off)</sub>	0		+1.0	V	$V_{DS} = 6 \text{ V}, V_{G2S} = 3 \text{ V}, I_{D} = 10 \mu A$
Gate2 to Source Cutoff Voltage	V <sub>G2S(off)</sub>	0		+1.0	V	$V_{DS} = 6 \text{ V}, V_{G2S} = 3 \text{ V}, I_{D} = 10 \mu A$
Gate1 Reverse Current	I <sub>G1SS</sub>			±20	nA	V <sub>DS</sub> = 0, V <sub>G2S</sub> = 0, V <sub>G1S</sub> = ±8 V
Gate2 Reverse Current	I <sub>G2</sub> ss			±20	nA	V <sub>DS</sub> = 0, V <sub>G1S</sub> = 0, V <sub>G2S</sub> = ±8 V
Forward Transfer Admittance	yfs	15	19.5		mS	V <sub>DS</sub> = 5 V, V <sub>G2S</sub> = 4 V, I <sub>D</sub> = 10 mA f = 1 kHz
Input Capacitance	Ciss	3.6	4.3	5.0	pF	V <sub>DS</sub> = 6 V, V <sub>G2S</sub> = 3 V, I <sub>D</sub> = 10 mA f = 1 MHz
Output Capacitance	CDSS	1.0	1.5	2.0	pF	
Reverse Transfer Capacitance	Crss		0.02	0.03	pF	
Power Gain	Gps	21.0	23.0		dB	V <sub>DS</sub> = 6 V, V <sub>G2S</sub> = 4 V, I <sub>D</sub> = 10 mA f = 200 MHz
Noise Figure 1	NF1		1.2	2.0	dB	
Noise Figure 2	NF2		1.0	2.0	dB	V <sub>DS</sub> = 6 V, V <sub>G2S</sub> = 4 V, I <sub>D</sub> = 10 mA f = 55 MHz

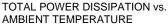
#### **IDSX Classification**

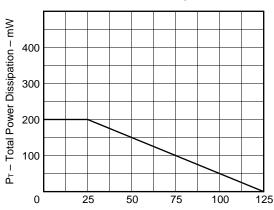
Class	V21/VBA*	V22/VBB*	
Marking	V21	V22	
IDSX (mA)	0.01 to 3.0	1.0 to 8.0	

<sup>\*</sup> Old specification/New specification

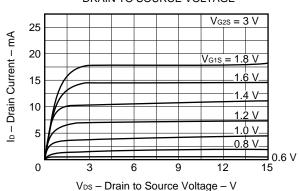
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#### TYPICAL CHARACTERISTICS (TA = 25 °C)



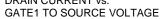


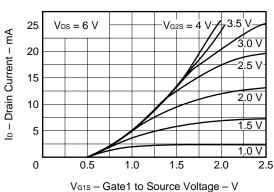
## DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE



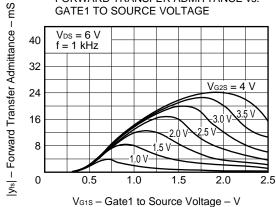
## DRAIN CURRENT vs.

T<sub>A</sub> – Ambient Temperature – °C

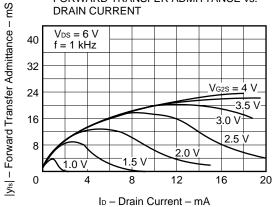




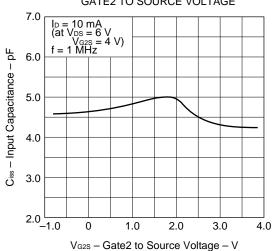
FORWARD TRANSFER ADMITTANCE vs.



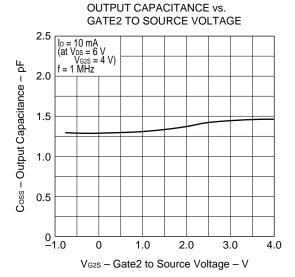
#### FORWARD TRANSFER ADMITTANCE vs. **DRAIN CURRENT**

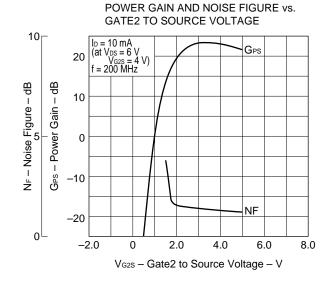


INPUT CAPACITANCE vs. **GATE2 TO SOURCE VOLTAGE** 

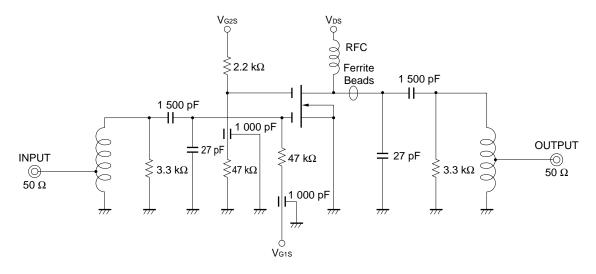




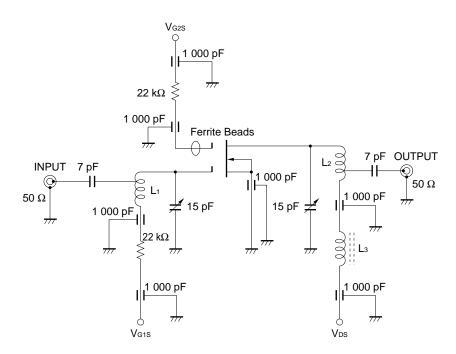




#### NF TEST CIRCUIT AT f = 55 MHz



#### GPS AND NF TEST CIRCUIT AT f = 200 MHz



L<sub>1</sub>: φ0.6 mm U.E.W φ7 mm 3 T

L<sub>2</sub>: φ0.6 mm U.E.W φ7 mm 3 T

L<sub>3</sub>: RFC 2.2 μH

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Anti-radioactive design is not implemented in this product.

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